1 Package summary

Terminal position code: B (bottom)
Package type descriptive code: LFBGA64
Package type industry code: LFBGA64
Package style descriptive code: LFBGA (low profile fine-pitch ball grid array)
Package body material type: P (plastic)
Mounting method type: S (surface mount)
Issue date: 08-01-2016
Manufacturer package code: 98ASA00420D

Table 1. Package summary

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Min</th>
<th>Nom</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>package length</td>
<td>-</td>
<td>5</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>package width</td>
<td>-</td>
<td>5</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>seated height</td>
<td>-</td>
<td>1.23</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>nominal pitch</td>
<td>-</td>
<td>0.5</td>
<td>-</td>
<td>mm</td>
</tr>
<tr>
<td>actual quantity of termination</td>
<td>-</td>
<td>64</td>
<td>-</td>
<td></td>
</tr>
</tbody>
</table>
2 Package outline

Figure 1. Package outline LFBGA64 (SOT1555-1)
NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.


3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.


5. PARALLEUSM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

Figure 2. Package outline note LFBGA64 (SOT1555-1)
3 Legal information

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